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Handcrafted Solutions For A High-Tech World

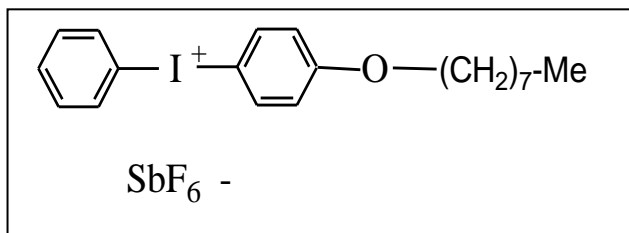
OPPI FP 5386

General

OPPI is a highly efficient UV curing agent used to initiate the photopolymerization of prepolymers in combination with mono or multifunctional monomers.

OPPI's unique composition provides excellent solubility, cure speed and high temperature stability, making it ideal for most epoxy based systems.

Chemical structure



Product information

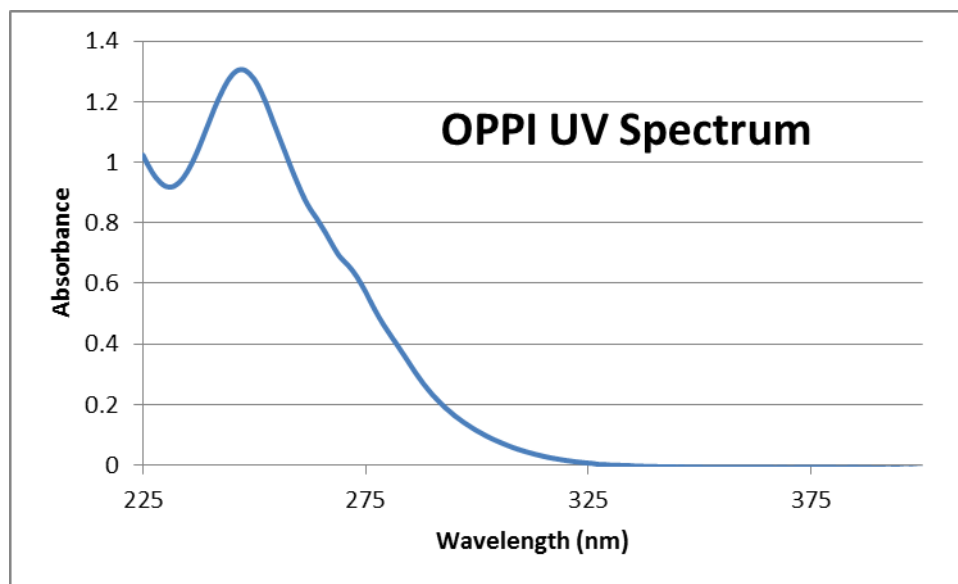
PRODUCT TYPE:	Photo Acid Generator
PRODUCT NAME:	(4-octyloxyphenyl) phenyliodonium hexafluoroantimonate
CAS NUMBER	121239-75-6
TRADE NAMES:	OPI, OPPI
APPLICATIONS:	Pressure Sensitive Adhesives, deep UV lithography,
KEY FEATURES:	Photo-acid generation for curing of epoxy and vinyl monomers. Also generates a free radical
PACKAGING:	sold as a solid or in reactive diluents
REGISTRATIONS:	TSCA (USA-CBI)
SHELF LIFE/STORAGE:	1 year when stored indoors at 25 (+/- 5) deg C

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Typical specifications

APPEARANCE: Off White Powder
MELTING POINT: 56-58 C

Absorption Spectrum



Suggested starting formulation

OPPI should be added between 1-3% for use with broad spectra mercury lamps. For LED applications, equal amounts of sensitizer (i.e. ITX or 9,10 DEA) should be used to help facilitate surface cure.

Safety and Handling

OPPI should be handled in accordance with good industrial practice. Detailed information is provided in the SDS.

OPPI is sensitive to visible light and any exposure to sunlight should be avoided.

Note: OPPI is also available with PF₆ and TPB counter ions

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